III B. Tech II Semester Regular Examinations, June-2022 VLSI DESIGN

(Electrical and Electronics Engineering)

Time: 3 hours Max. Marks: 75

Answer any **FIVE** Questions **ONE** Question from **Each unit**All Questions Carry Equal Marks

UNIT-I								
1.	a)	Outline the DC transfer characteristics of CMOS inverter.	[8M]					
	b)	An nMOSFET is operating in saturation region with the following	[7M]					
		parameters:						
		$V_{GS} = 5 \text{ V}, V_{tn} = 1.1 \text{ V}, W/L = 120, \mu_n C_{ox} = 120 \mu A/V$						
		Find the Drain resistance of the device.						
0	(OR)	[0] [
2.	a)	Describe the operation of enhancement mode NMOS transistor using its characteristics.	[8M]					
	b)	Realize CMOS inverter and describe its operation.	[7M]					
	UNIT-II							
3.	a)	Summarize the fabrication steps of N Well process with neat	[8M]					
	1. \	diagram.	[/7]]					
	b)	What is the need of oxidation process in MOS transistor	[7M]					
		fabrication and list the types of oxidations. (OR)						
4.	a)	List the typical fabrication steps involved in MOS transistor	[8M]					
т.	aj	fabrication.	[OWI]					
	b)	Compare diffusion and ion implantation.	[7M]					
	UNIT-III							
5.	a)	Model the static CMOS layout for the expression F= (A+B)'.	[8M]					
	b)	Develop a 2-input XOR gate using pass transistor logic.	[7M]					
	(OR)							
6.	a)	Construct the stick diagram for NMOS NAND gate.	[8M]					
	b)	Design two bit comparator using Pass transistor or Transmission	[7M]					
		gate.						
<u>UNIT-IV</u>								
7.	a)	Develop the SR Latch with true single phase clock systems.	[8M]					
	b)	Design DFF using Transmission gate.	[7M]					

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8.	a)	Demonstrate the sources of clock skew with neat diagrams.	[8M]
	b)	Illustrate the operation of single transistor DRAM cell.	[7M]
		UNIT-V	
9.	a)	Define simulation and list the possible types of simulations in	[8M]
		ASIC design.	
	b)	Describe Floor planning using diagram of ASIC design sequence.	[7M]
		(OR)	
10.	a)	Draw the ASIC design flow and describe the backend design	[8M]
		process.	
	b)	Define circuit extraction, in which stage of the ASIC design flow	[7M]
		circuit extraction is the best.	

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